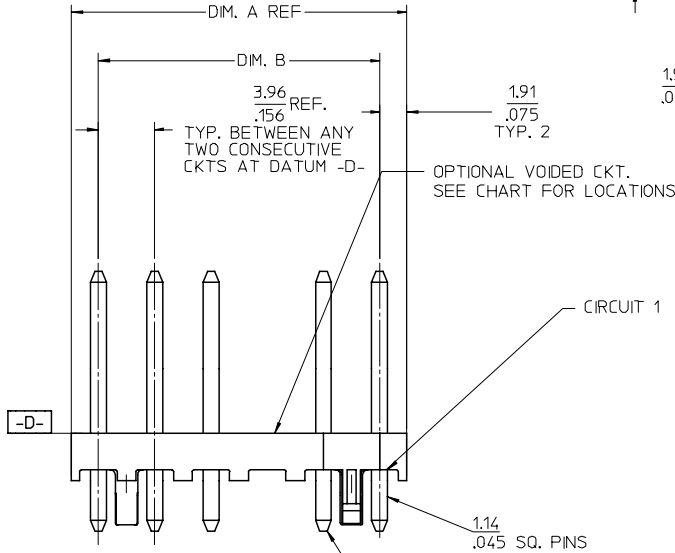
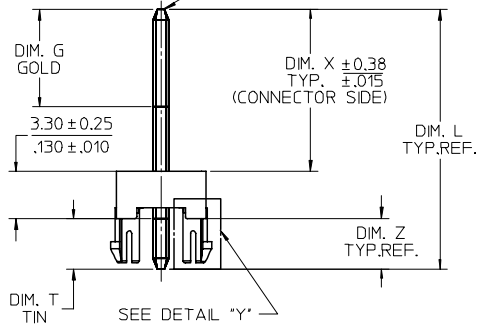
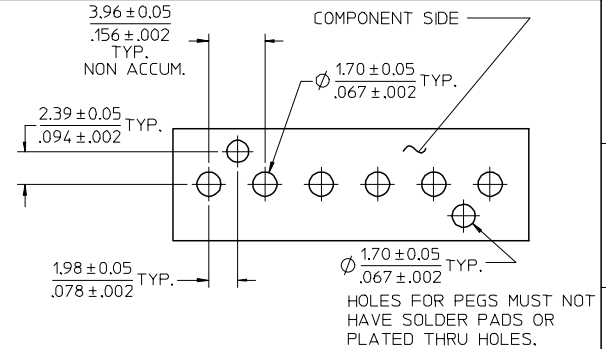
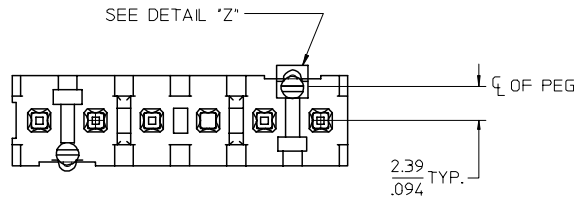


CENTERLINE OF PIN AT TIP
NOT TO VARY FROM CENTERLINE OF
PIN AT DATUM -D- BY MORE THAN
0.20/.008 IN ANY DIRECTION.



CENTERLINE OF PIN AT TIP
NOT TO VARY FROM CENTERLINE OF
PIN AT DATUM -D- BY MORE THAN
0.13/.005 IN ANY DIRECTION.



RECOMMENDED PC BOARD HOLE LAYOUT

FOR CORRECT ORIENTATION OF PARTS WITH
VOIDS, ELIMINATE CORRESPONDING PCB HOLE.
(FOR 1.57/.062 THIK PCB)

NO. OF CKTS.	NO. OF PEGS	DIM. A	DIM. B
2	1	7.77 3.06	3.96 ± 0.05 .156 ± 0.002
3	2	11.73 .462	7.92 ± 0.08 .312 ± 0.003
4	2	15.70 .618	11.89 ± 0.08 .468 ± 0.003
5	2	19.66 .774	15.85 ± 0.10 .624 ± 0.004
6	2	23.62 .930	19.81 ± 0.10 .780 ± 0.004
7	2	27.58 1.086	23.77 ± 0.10 .936 ± 0.004
8	2	31.55 1.242	27.74 ± 0.13 1.092 ± 0.005
9	2	35.51 1.398	31.70 ± 0.13 1.248 ± 0.005
10	2	39.47 1.554	35.66 ± 0.13 1.404 ± 0.005
11	2	43.43 1.710	39.62 ± 0.15 1.560 ± 0.006
12	2	47.40 1.866	43.59 ± 0.15 1.716 ± 0.006
13	2	51.36 2.022	47.55 ± 0.15 1.872 ± 0.006
14	2	55.32 2.178	51.51 ± 0.18 2.028 ± 0.007
15	2	59.28 2.334	55.47 ± 0.18 2.184 ± 0.007
16	2	63.25 2.490	59.44 ± 0.18 2.340 ± 0.007
17	2	67.21 2.646	63.40 ± 0.20 2.496 ± 0.008
18	2	71.17 2.802	67.36 ± 0.20 2.652 ± 0.008

NOTES:

- MATERIAL: HEADER-GLASS FILLED POLYESTER, 94V-0, MOLDED NATURAL (WHITE).
- FINISHES: (102) OVERALL TIN: (0.00508)/.000200 MIN.
OVERALL COPPER UNDERPLATE: (0.00254)/.000100 MIN.
(208) SELECT GOLD: (0.00038)/.000015 MIN.,
*SELECT TIN: (0.00254)/.000100 MIN.,
OVERALL NICKEL UNDERPLATE: (0.00127)/.000050 MIN.
(228) SELECT GOLD: (0.00076)/.000030 MIN.,
*SELECT TIN: (0.00254)/.000100 MIN.,
OVERALL NICKEL UNDERPLATE: (0.00127)/.000050 MIN.
(501) OVERALL GOLD: (0.0051)/.000020 MIN.
OVERALL NICKEL UNDERPLATE: (0.00076)/.000030 MIN.

* THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO
RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 000/53/EC
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN/LEAD PLATINGS.

- PRODUCT SPECIFICATION: SEE PS-08-50.
- PACKAGING SPECIFICATION: SEE CHARTS
- PARTS ARE STACKABLE END TO END ON (3.96)/.156 CENTERS.
- FOR PARTS WITHOUT PEGS, SEE DRAWING SDA-41771.
- SOLDERABILITY: WHEN PARTS ARE SOLDERED AT A TEMPERATURE OF (230°C) OR (446°F) FOR 5 SECONDS, EACH SOLDERED SURFACE SHALL BE A MINIMUM OF 95% COVERED WITH A SMOOTH CONTINUOUS ADHERENT COATING. FOR OTHER INFORMATION SEE SMES-152.
- PIN PUSH OUT FORCE: PRIOR TO SOLDERING, A 3 LB MINIMUM FORCE (IN EITHER DIRECTION) SHALL BE REQUIRED TO PUSH THE PIN OUT OF THE HEADER.
- 6 CIRCUIT PART SHOWN.
- THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

UPDATE NOTES FC NO: UCP2007-2132 DRAWN/RI/DER 2007/03/24 CHKD:ADERR 2007/03/27 APPR:FSM/TH 2007/03/28	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION			
		4 PLACES \pm --- \pm --- 3 PLACES \pm --- \pm --- 2 PLACES \pm --- \pm --- 1 PLACE \pm --- \pm ---	mm INCH	DRAWN BY SAMIEC	DATE 1991/01/14	TITLE FLAT HEADER ASSEMBLY (3.96)/.156 CENTERS, SQ STRAIGHT PINS, W/ PEGS					
		ANGULAR $\pm 1/2^\circ$		CHECKED BY PATEL	DATE 1991/01/14	MATERIAL LENZ					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY LENZ	DATE 1991/01/14	MOLEX INCORPORATED		DOCUMENT NO. SD-42871-001	SHEET NO. 1 OF *		

